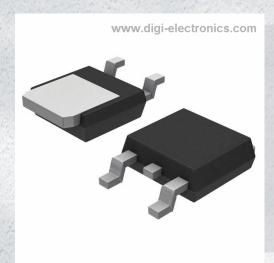


# NJVMJD210T4G Datasheet



https://www.DiGi-Electronics.com

DiGi Electronics Part Number NJVMJD210T4G-DG

Manufacturer onsemi

Manufacturer Product Number NJVMJD210T4G

Description TRANS PNP 25V 5A DPAK

Detailed Description Bipolar (BJT) Transistor PNP 25 V 5 A 65MHz 1.4 W S

urface Mount DPAK



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RFQ Email: Info@DiGi-Electronics.com

DiGi is a global authorized distributor of electronic components.



## **Purchase and inquiry**

Manufacturer Product Number:	Manufacturer:
NJVMJD210T4G	onsemi
Series:	Product Status:
	Active
Transistor Type:	Current - Collector (Ic) (Max):
PNP	5 A
Voltage - Collector Emitter Breakdown (Max):	Vce Saturation (Max) @ lb, Ic:
25 V	1.8V @ 1A, 5A
Current - Collector Cutoff (Max):	DC Current Gain (hFE) (Min) @ lc, Vce:
100nA (ICBO)	45 @ 2A, 1V
Power - Max:	Frequency - Transition:
1.4 W	65MHz
Operating Temperature:	Mounting Type:
-65°C ~ 150°C (TJ)	Surface Mount
Package / Case:	Supplier Device Package:
TO-252-3, DPAK (2 Leads + Tab), SC-63	DPAK
Base Product Number:	
NJVMJD210	

## **Environmental & Export classification**

RoHS Status:	Moisture Sensitivity Level (MSL):
ROHS3 Compliant	1 (Unlimited)
REACH Status:	ECCN:
REACH Unaffected	EAR99
HTSUS:	
8541.29.0075	

## **Complementary Plastic Power Transistors**

NPN/PNP Silicon DPAK For Surface **Mount Applications** 

## **MJD200 (NPN),** MJD210 (PNP)

Designed for low voltage, low-power, high-gain audio amplifier applications.

#### **Features**

- High DC Current Gain
- Lead Formed for Surface Mount Applications in Plastic Sleeves (No Suffix)
- Low Collector-Emitter Saturation Voltage
- High Current-Gain Bandwidth Product
- Annular Construction for Low Leakage
- Epoxy Meets UL 94 V-0 @ 0.125 in
- NJV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

### **MAXIMUM RATINGS**

Rating	Symbol	Max	Unit
Collector-Base Voltage	V <sub>CB</sub>	40	Vdc
Collector-Emitter Voltage	V <sub>CEO</sub>	25	Vdc
Emitter-Base Voltage	V <sub>EB</sub>	8.0	Vdc
Collector Current - Continuous	I <sub>C</sub>	5.0	Adc
Collector Current - Peak	I <sub>CM</sub>	10	Adc
Base Current	Ι <sub>Β</sub>	1.0	Adc
Total Power Dissipation @ T <sub>C</sub> = 25°C Derate above 25°C	P <sub>D</sub>	12.5 0.1	W W/°C
Total Power Dissipation (Note 1) @ T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	1.4 0.011	W W/°C
Operating and Storage Junction Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-65 to +150	°C
ESD - Human Body Model	HBM	3B	V
ESD - Machine Model	MM	С	V

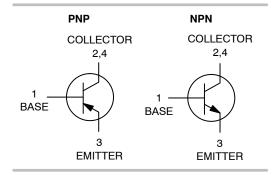
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



### ON Semiconductor®

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## SILICON **POWER TRANSISTORS 5 AMPERES 25 VOLTS, 12.5 WATTS**





#### **MARKING DIAGRAM**



= Assembly Location

= Year

= Work Week

x = 1 or 0

= Pb-Free Package

### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

### THERMAL CHARACTERISTICS

Characteristic		Max	Unit
Thermal Resistance, Junction-to-Case	$R_{ heta JC}$	10	°C/W
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	89.3	°C/W

1

<sup>1.</sup> These ratings are applicable when surface mounted on the minimum pad sizes recommended.

<sup>2.</sup> These ratings are applicable when surface mounted on the minimum pad sizes recommended.

## **ELECTRICAL CHARACTERISTICS** (T<sub>C</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS			1	
Collector–Emitter Sustaining Voltage (Note 3) (I <sub>C</sub> = 10 mAdc, I <sub>B</sub> = 0)	V <sub>CEO(sus)</sub>	25	-	Vdc
Collector Cutoff Current $(V_{CB} = 40 \text{ Vdc}, I_E = 0)$ $(V_{CB} = 40 \text{ Vdc}, I_E = 0, T_J = 125^{\circ}\text{C})$	I <sub>CBO</sub>	_ _ _	100 100	nAdc μAdc
Emitter Cutoff Current (V <sub>BE</sub> = 8 Vdc, I <sub>C</sub> = 0)	I <sub>EBO</sub>	-	100	nAdc
ON CHARACTERISTICS				
C Current Gain (Note 3), $ \begin{array}{l} (I_C=500 \text{ mAdc, } V_{CE}=1 \text{ Vdc)} \\ (I_C=2 \text{ Adc, } V_{CE}=1 \text{ Vdc)} \\ (I_C=5 \text{ Adc, } V_{CE}=2 \text{ Vdc)} \end{array} $	h <sub>FE</sub>	70 45 10	- 180 -	-
	V <sub>CE(sat)</sub>	- - -	0.3 0.75 1.8	Vdc
Base-Emitter Saturation Voltage (Note 3) (I <sub>C</sub> = 5 Adc, I <sub>B</sub> = 1 Adc)	V <sub>BE(sat)</sub>	-	2.5	Vdc
Base–Emitter On Voltage (Note 3) (I <sub>C</sub> = 2 Adc, V <sub>CE</sub> = 1 Vdc)	V <sub>BE(on)</sub>	-	1.6	Vdc
DYNAMIC CHARACTERISTICS				
Current-Gain - Bandwidth Product (Note 4) (I <sub>C</sub> = 100 mAdc, V <sub>CE</sub> = 10 Vdc, f <sub>test</sub> = 10 MHz)	f <sub>T</sub>	65	-	MHz
Output Capacitance (V <sub>CB</sub> = 10 Vdc, I <sub>E</sub> = 0, f = 0.1 MHz) MJD200 MJD210, NJVMJD210T4G	C <sub>ob</sub>	- -	80 120	pF

<sup>3.</sup> Pulse Test: Pulse Width = 300  $\mu$ s, Duty Cycle  $\approx$  2%.

<sup>4.</sup>  $f_T = |h_{fe}| \cdot f_{test}$ 

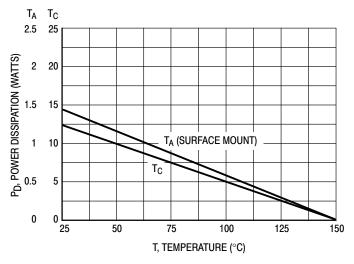
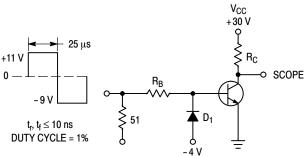


Figure 1. Power Derating



 ${\rm R}_{\rm B}$  and  ${\rm R}_{\rm C}$  varied to obtain desired current levels

D<sub>1</sub> MUST BE FAST RECOVERY TYPE, e.g.: 1N5825 USED ABOVE I<sub>B</sub>  $\approx$  100 mA FOR PNI MSD6100 USED BELOW I<sub>B</sub>  $\approx$  100 mA REVERSE

FOR PNP TEST CIRCUIT, REVERSE ALL POLARITIES

Figure 2. Switching Time Test Circuit

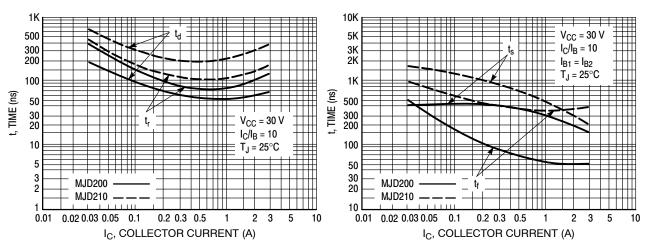


Figure 3. Turn-On Time

Figure 4. Turn-Off Time

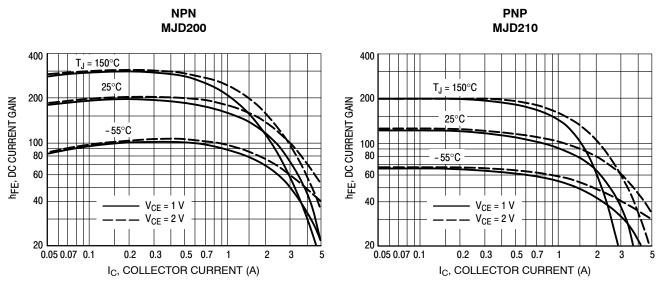


Figure 5. DC Current Gain

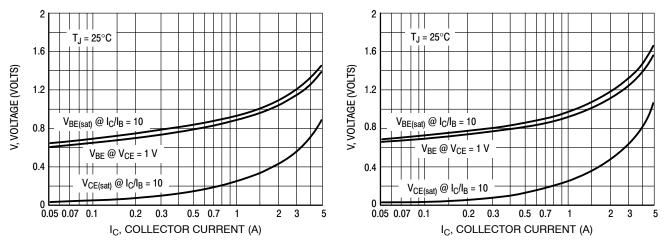
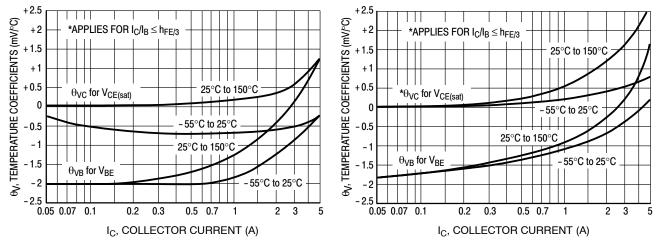


Figure 6. "On" Voltage



**Figure 7. Temperature Coefficients** 

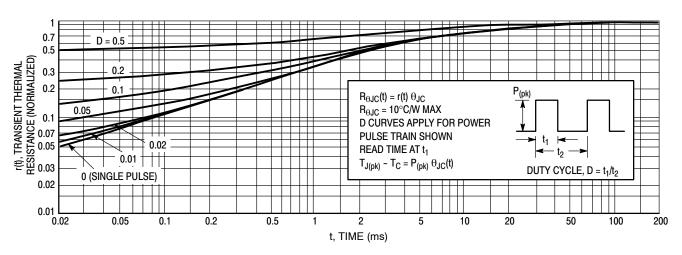


Figure 8. Thermal Response

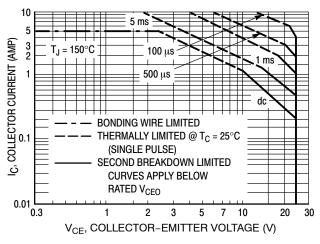


Figure 9. Active Region Safe Operating Area

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate  $I_C$  –  $V_{CE}$  limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 9 is based on  $T_{J(pk)} = 150^{\circ}C$ ;  $T_C$  is variable depending on conditions. Second breakdown pulse limits are valid for duty cycles to 10% provided  $T_{J(pk)} \le 150^{\circ}C$ .  $T_{J(pk)}$  may be calculated from the data in Figure 8. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

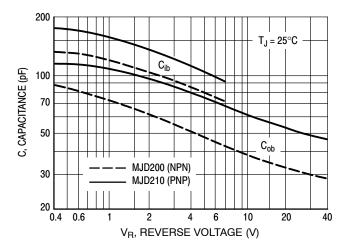


Figure 10. Capacitance

### **ORDERING INFORMATION**

Device	Package Type	Shipping <sup>†</sup>
MJD200G	DPAK (Pb-Free)	75 Units / Rail
MJD200RLG	DPAK (Pb-Free)	1,800 / Tape & Reel
MJD200T4G	DPAK (Pb-Free)	2,500 / Tape & Reel
MJD210G	DPAK (Pb-Free)	75 Units / Rail
MJD210RLG	DPAK (Pb-Free)	1,800 / Tape & Reel
MJD210T4G	DPAK (Pb-Free)	2,500 / Tape & Reel
NJVMJD210T4G*	DPAK (Pb-Free)	2,500 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*NJV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP

Capable

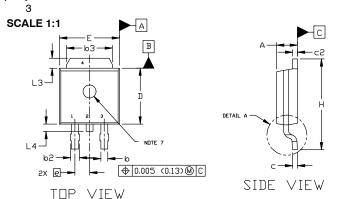


## **MECHANICAL CASE OUTLINE**

## PACKAGE DIMENSIONS

### **DPAK (SINGLE GAUGE)** CASE 369C ISSUE G

**DATE 31 MAY 2023** 



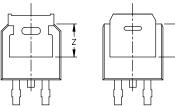


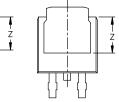
- DIMENSIONING AND TOLERANCING ASME Y14.5M, 1994. CONTROLLING DIMENSION: INCHES
- THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS 63, L3. AND Z.
- L3, AND Z.

  DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH,
  PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR
  GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
  DIMENSIONS D AND E ARE DETERMINED AT THE
  OUTERMOST EXTREMES OF THE PLASTIC BODY.
  DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.
  DETININAL MOLD ESCALUPE.

- OPTIONAL MOLD FEATURE.

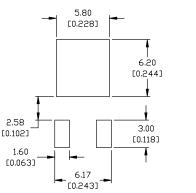
DIM	INCHES		MILLIMETERS	
ויונע	MIN.	MAX.	MIN.	MAX.
Α	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.028	0.045	0.72	1.14
b3	0.180	0.215	4.57	5.46
C	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
Ε	0.250	0.265	6.35	6.73
е	0.090	0.090 BSC		BSC
Н	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.114 REF		2.90	REF
L2	0.020 BSC		0.51	BSC
L3	0.035	0.050	0.89	1.27
L4		0.040		1.01
Z	0.155		3.93	

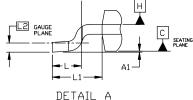




BOTTOM VIEW

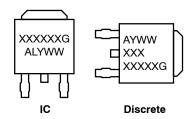
BOTTOM VIEW ALTERNATE CONSTRUCTIONS





CW ROTATED 90°

### **GENERIC MARKING DIAGRAM\***



XXXXXX	= Device Code
Α	= Assembly Location
L	= Wafer Lot
Υ	= Year
WW	= Work Week
G	= Pb-Free Package

\*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DUWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

RECOMMENDED MOUNTING FOOTPRINT\*

022	LE 3: STYLE 4: I 1. ANODE PIN 1. CATH 2. CATHODE 2. ANO 3. ANODE 3. GATH 4. CATHODE 4. ANO	DE 2. ANODE E 3. CATHODE
-----	--	-----------------------------

STYLE 7: PIN 1. GATE 2. COLLECTOR STYLE 6: STYLE 8: STYLE 9: STYLE 10: PIN 1. CATHODE 2. ANODE 3. CATHODE PIN 1. MT1 2. MT2 PIN 1. N/C 2. CATHODE 3. ANODE PIN 1. ANODE 2. CATHODE 3 FMITTER 3 RESISTOR ADJUST 3 GATE 4. COLLECTOR 4. CATHODE 4. ANODE 4. CATHODE

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	DPAK (SINGLE GAUGE)		PAGE 1 OF 1

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